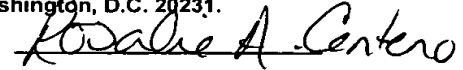


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Rosalie A. Centeno, Secretary

In the application of : Ulrich Speh, et al
Serial Number: Not Assigned
Filing Date: January 22, 2002
For: APPARATUS FOR TREATING SUBSTRATES
Assistant Commissioner for Patents
Washington, DC 20231

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 CFR § 1.56, Applicant wishes to call the attention of the Examiner to the following references:

- 1) EP 0 817 246 A2
- 2) JP 5-291223 (A)
- 3) JP 06005577
- 4) JP 03020031
- 5) US 5,503,171
- 6) US 5,203,798
- 7) JP 6-73598 (A)
- 8) US 5,836,325
- 9) JP 6-244164 (A)
- 10) JP 10308376 (A)
- 11) DE 196 16 400
- 12) JP 62-279640 (A)
- 13) JP 5-166793 (A)
- 14) JP 10163158 A

- 15) JP 10163164
- 16) JP 07066100 A
- 17) JP 4-10416 (A)
- 18) JP 06326067 (A)

The relevance of references 1 and 2 has been discussed in the instant specification on page

1.

References 3 – 6 have been cited in the International Search Report and are submitted to provide the Examiner easy access to said references.

References 7-10 and 12-18 are in the English language and need no further discussion as to their relevance.

Reference 11, DE 196 16 400 A1, discloses a device for the treatment of substrates in a fluid container having at least one fluid inlet opening and at least one overflow opening in an upper area of a sidewall. The surface of the overflow opening is changeable, in order to provide an optimal adjustment of the fluid revolution rate. Preferably, the changing of the surface of the overflow opening is accomplished by means of a slider.

Copies of the listed documents are submitted herewith along with the form PTO-1449. It is respectfully requested that any fees required and not enclosed herewith or any shortages in any fees be charged to Deposit Account 02-1653.

Consideration of the foregoing in relation to this application is respectfully requested.

Respectfully submitted,



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for the Applicant

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RWB/rac
Enclosures: PTO 1449
reference(s)

INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Complete if Known	
	Application Number	
	Filing Date	January 22, 2002
	First Named Inventor	Ulrich Speh, et al
	Group Art Unit	
	Examiner Name	
	Attorney Docket No.	Az.3049

U. S. PATENT DOCUMENTS							
Examiner Initials	Cite No.	Patent Number	Issue Date	Patentee	Class	Subclass	Filing Date
	5	5,503,171	04/02/1996	Yokomizo et al			12/22/1993
	6	5,203,798	04/20/1993	Watanabe et al			06/24/1991
	8	5,836,325	11/17/1998	Akanuma et al			09/16/1996

FOREIGN PATENT DOCUMENTS							
Examiner Initials	Cite No.	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation
							Yes No
	1	EP0817246A1	07 Jan 1998	Europe			X
	11	DE19616400	06 Nov 1997	Germany			X

OTHER PRIOR ART _B NON PATENT LITERATURE DOCUMENTS		
Examiner Initials	Cite No.	
	2	JP 5-291223, Water Cleaning Apparatus
	3	JP 06005577, Substrate Cleaning Device
	4	JP 03020031, Ultrasonic Cleaning Device
	7	JP 6-73598, Method for Producing Semi-conductor and Device Thereof
	9	JP 6-244164 (1), Ultrasonic Cleaning Device
	10	JP 10308376 (A) Cleaning of Wafer and Wafer Cleaning Device
	12	JP 62-279640, Wafer Washing Apparatus
	13	JP 5-166793 (A) Dipping Type Substrate Treatment Apparatus
	14	JP 10163158 A Cleaning Apparatus for Sheetlike Body
	15	JP 10163164 A Substrate Treatment Method and Substrate Treatment Apparatus
	16	JP 07066100 A Air Knife and Processor Using the Same
	17	JP 4-10416 (A) Method and Apparatus for Drying Substrate
	18	JP 06326067 A Substrate Treatment Apparatus

Examiner		Date	
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1/22/02